

Polishing Slurry

Machplaner™

Machplaner™ MS2000 Series are for sapphire polishing, MS3000 Series are for LiTaO₃/LiNbO₃ polishing, ST2000 is for glass polishing. These slurries achieve high removal rate and good surface quality with optimization of particle design.

Machplaner™ Series

Physical Property

	MS2020	MS2100	MS3000 ※1	ST2010	MS4100
Particle Type	Colloidal Silica				Alumina
Silica wt%	38.0	50.0	50.0	22.5	
pH	9.0-9.5	8.2-9.2	9.0-10.0	10.5-11.5	13.5
Particle Size(nm)	60-120	100-160	80-120	110-170	180-220
Specific Gravity	1.10-1.40	1.36-1.40	1.36-1.40	1.08-1.20	1.00-1.10
Dilution Ratio	2 times	3 times	2.5 times	Ready to use	Ready to use
Application	Sapphire c-plane	Sapphire a-plane	LiTaO ₃ LiNbO ₃	Glass	Resin
Advantages	Reduce a friction, Lower pad temperature	Optimized to high pressure polish	2 parts type (pH3.0-5.0) High RR	Surface roughness reduction	High RR High selectivity to other materials

※1 : This product is 2 components. The above data is shown as a physical property of A part.

- ▣ Machplaner™ slurry achieves high removal rate and good surface quality with optimization of particle and additive design.
- ▣ Other applications such as Sapphire, Glass, Crystal, Oxide Materials and Resin are also covered by each polishing target.
- ▣ Free sample is available for first evaluation.



※ Machplaner™ is the trademark of Nitta Haas Incorporated.

※ The values such as a physical property indicated, show the standard value. The product specifications are not guaranteed.